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EMIF02-USB05F2

2 line EMF filter including ESD protection

Main application

When EMI filtering is ESD sensitive equipment is required:

- Mobile phones and communication systems
- Computers, printers and MCU boards

Description

The EMIF02-USB05F2 is a highly integrated array designed to suppress EMI / RFI noise for USB port filtering. The EMIF02-USB05F2 Flip-Chip packaging means the package size is equal to the die size.

Additionally, this low-pass filter includes an ESD protection circuitry to prevent damage to the application when subjected to ESD surges up to 15 kV.

This device is designed to be fully compatible with USB standards.

Benefits

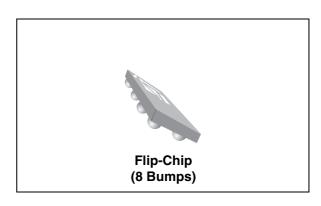
- 2 x EMI low-pass filter + 2 line ESD protection
- 1.5 kΩ pull-up included
- High efficiency in EMI filtering
- Lead free package
- Very low PCB space consumption: 1.92 mm x 0.92 mm
- Very thin package: 0.65 mm
- High reliability offered by monolithic integration
- High reduction of parasitic elements through integration and wafer level packaging
- USB full speed (12 Mbps), OTG compliant

Complies with following standards:

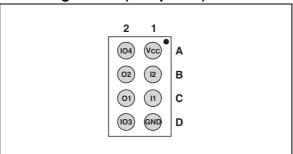
IEC 61000-4-2

level 4 15 kV (air discharge) 8 kV (contact discharge)

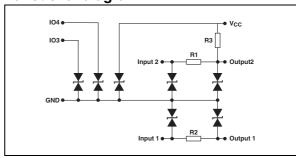
MIL STD 883G - Method 3015-7 Class 3



Pin configuration (bump side)



Functional diagram



Order code

Part Number	Marking		
EMIF02-USB05F2	GV		

TM: IPAD is a trademark of STMicroelectronics

Characteristics EMIF02-USB05F2

1 Characteristics

 Table 1.
 Absolute ratings (limiting values)

Symbol	Parameter and test conditions	Value	Unit
T _j	Maximum junction temperature	125	° C
T _{op}	Operating temperature range	- 40 to + 85	° C
T _{stg}	Storage temperature range	- 55 to + 150	° C

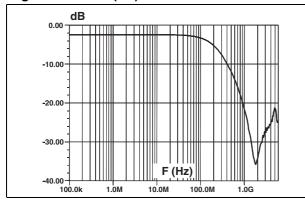
Table 2. Electrical characteristics (Tamb = 25° C)

Symbol	Parameter	' <u>†</u>
V _{BR}	Breakdown voltage	
I _{RM}	Leakage current @ V _{RM}	VBR VRM IRM IRM VRM VBR
V _{RM}	Stand-off voltage	
C _{line}	Input capacitance per line	

Symbol	Test conditions	Tolerance	Min.	Тур.	Max.	Unit
V _{BR}	I _R = 1 mA		6		9	V
I _{RM}	V _{RM} = 5 V per line				1	μΑ
R ₁ , R ₂	I = 10 mA	± 5%		33		Ω
R_3	I = 1 mA	± 5%		1.5		kΩ
C _{line}	@ 0 V			30		pF
Matching	Serial resistance matching			1		%

EMIF02-USB05F2 Characteristics

Figure 1. S21 (dB) attenuation measurement Figure 2. Analog crosstalk measurements



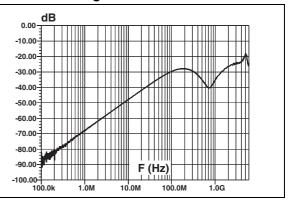
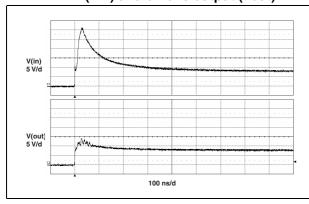


Figure 3. ESD response to IEC 61000-4-2 (+15 kV air discharge) on one input (Vin) and on one output (Vout)

Figure 4. ESD response to IEC 61000-4-2 (-15 kV air discharge) on one input (Vin) and on one output (Vout)



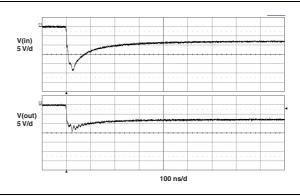
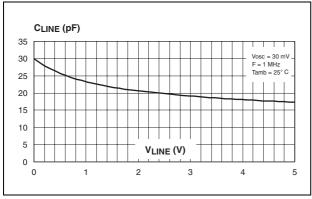


Figure 5. Junction capacitance versus reverse voltage applied



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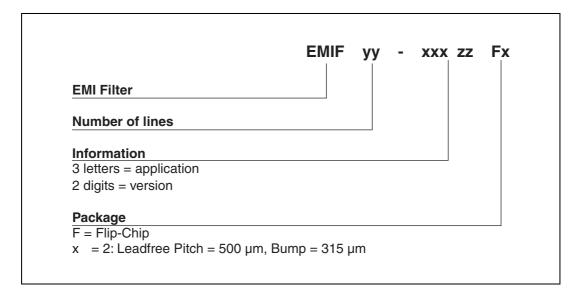
Lbump Rbump -0 D2 A2 B1 Rbump Lbump R1 Lbump Rbump Rbump Rbump D1 Lbump Lbump MODEL Lbump MODEL = D1 \pm MODEL = D1 **o** bulk **o** bulk **b**ulk Rbump MODEL = D1 ☆ R2 Lbump Rbump C2 C1 Rbump Lbump Lgnd bulk bulk Cgnd Rgnd MODEL = D1 ☆ MODEL = D1

Figure 6. Aplac model device structure

Figure 7. Aplac model parameters

	aplacvar R1 33 aplacvar R2 33 aplacvar R3 1.5k aplacvar Cz_D1 15pF aplacvar Rs_D1 1 aplacvar Cz_D2 300pF aplacvar Rs_D2 0.3 aplacvar Lgnd 100pH aplacvar Rgnd 100m aplacvar Cgnd 0.4pF aplacvar Rbump 50pH aplacvar Rbump 20m	Diode D1 BV=7 IBV=1 m CJO=Cz_d1 M=0.3333 RS=Rs_d1 VJ=0.6 TT=100n	Diode D2 BV=7 IBV=1m CJO=Cz_d2 M=0.3333 RS=Rs_d2 VJ=0.6 TT=100n
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2 Ordering information scheme



EMIF02-USB05F2 Package information

3 Package information

Figure 8. Flip-Chip package dimensions

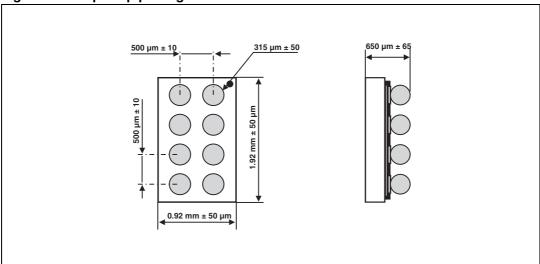


Figure 9. Foot print recomendations Figure 10. Marking

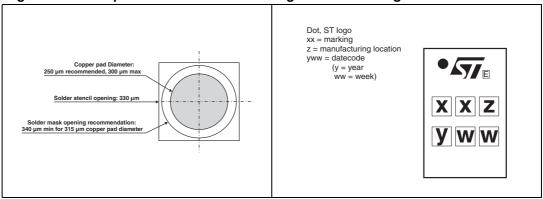
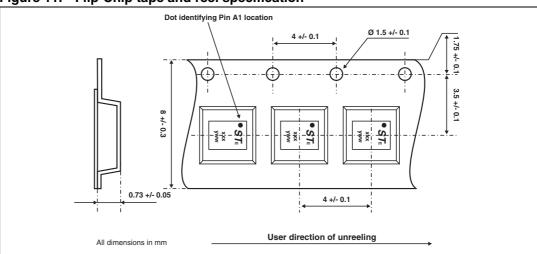


Figure 11. Flip-Chip tape and reel specification



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Note: More packing information is available in the application notes

AN1235: "Flip-Chip: Package description and recommendations for use"

AN1751: "EMI Filters: Recommendations and measurements"

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF02-USB05F2	GV	Flip-Chip	2.7 mg	5000	Tape and reel 7"

5 Revision history

Date	Revision	Changes	
14-Mar-2005	1	Initial release.	
13-Nov-2006	2	Reformatted to current standards. Modified functional diagram on page 1 to show connections. Updated Aplac model information.	

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